

ABSTRACT

This mounting device is for mounting a chip component on a substrate via a paste and includes: an application unit (16) that applies a paste on a substrate under predetermined application conditions to form an application body; a bonding unit (18) that forms a mounted body
5 which is the substrate having a chip component mounted thereon under predetermined mounting conditions via the application body; a first imaging unit (38) that images the application body after applying the paste and before mounting the chip component to obtain first image information; a second imaging unit (42) that images the mounted body after the mounting to obtain second image information; and a control unit (22) that controls the application unit (16), the bonding unit (18),
10 and the first and second imaging units (38), (42) and determines a three-dimensional shape of the application body from the first image information as a first shape and calculates a three-dimensional shape of the mounted body from the second image information as a second shape, wherein the control unit (22) evaluates the application or the mounting on the basis of the first shape and the second shape.

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FIGURE 1